# XP0121N

### Silicon NPN epitaxial planar type

For digital circuits

#### Features

- Two elements incorporated into one package (Emitter-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

### Basic Part Number

• UNR221N  $\times$  2

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	50	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	50	v	
Collector current	I <sub>C</sub>	100	mA	
Total power dissipation	P <sub>T</sub>	150	mW	
Junction temperature	Тј	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 50 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 50 \text{ V}, I_B = 0$			0.5	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 6 V, I_C = 0$			0.2	mA
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 10 \text{ V}, I_C = 5 \text{ mA}$	80		400	
h <sub>FE</sub> Ratio *	h <sub>FE(Small</sub> /Large)	$V_{CE} = 10 \text{ V}, I_C = 5 \text{ mA}$	0.50	0.99		
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0.3 \text{ mA}$			0.25	V
Output voltage high-level	V <sub>OH</sub>	$V_{CC} = 5 \text{ V},  \text{V}_{B} = 0.5  \text{V},  \text{R}_{L} = 1  \text{k} \Omega$	4.9			V
Output voltage low-level	V <sub>OL</sub>	$V_{CC} = 5 \text{ V},  \text{V}_{B} = 2.5  \text{V},  \text{R}_{L} = 1  \text{k} \Omega$			0.2	V
Input resistance	R <sub>1</sub>		-30%	4.7	+30%	kΩ
Resistance ratio	R <sub>1</sub> / R <sub>2</sub>			0.1		_
Transition frequency	f <sub>T</sub>	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. \*: Ratio between 2 elements

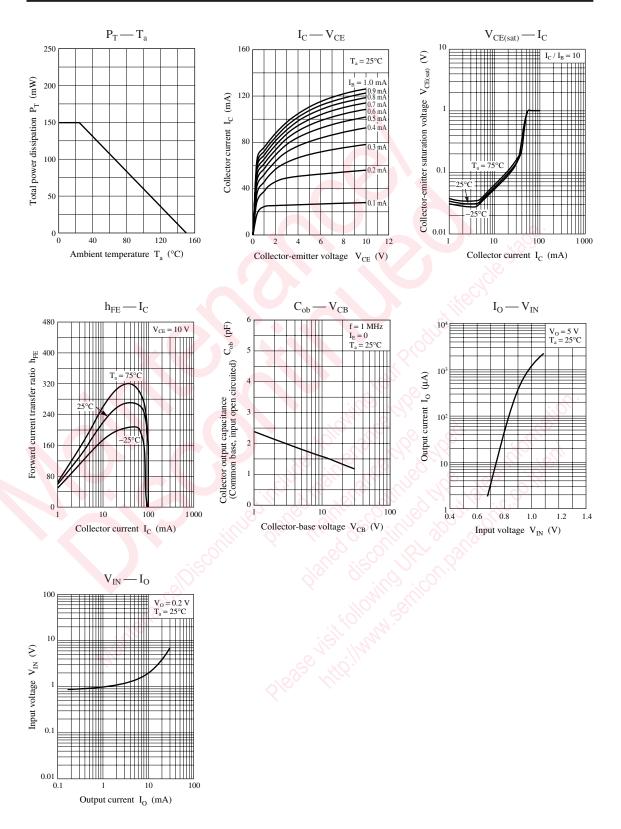
- PackageCode
- Code
  SMini5-G1
- Pin Name
- 1: Base (Tr1)
  - 1) 4: Col
  - 2: Emitter 3: Base (Tr2)
- 4: Collector (Tr2)
- 5: Collector (Tr1)

Marking Symbol: HN

Internal Connection

### XP0121N

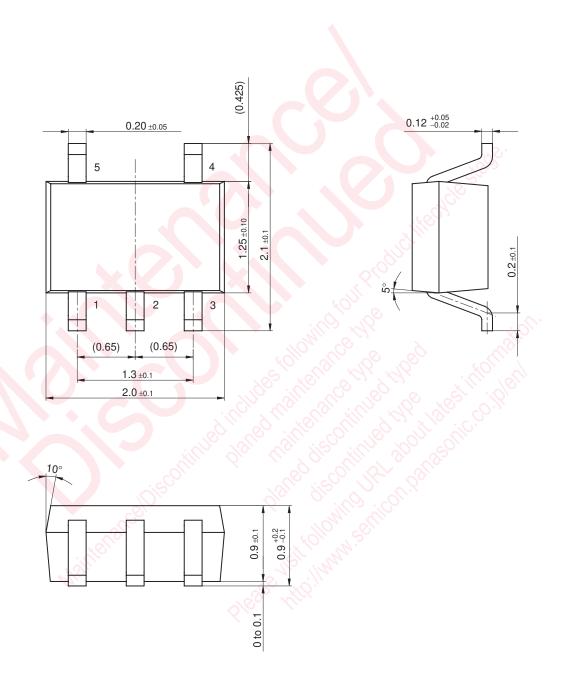




# Panasonic

## SMini5-G1

Unit: mm



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